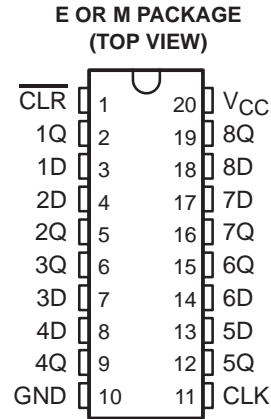


# CD74FCT273 BiCMOS OCTAL D-TYPE FLIP-FLOP WITH RESET

SCBS737A – JULY 2000 – REVISED JULY 2000

- BiCMOS Technology With Low Quiescent Power
- Buffered Inputs
- Direct Clear Input
- 48-mA Output Sink Current
- Output Voltage Swing Limited to 3.7 V
- Controlled Output Edge Rates
- Input/Output Isolation From  $V_{CC}$
- SCR Latch-Up-Resistant BiCMOS Process and Circuit Design
- Applications Include:
  - Buffer/Storage Registers
  - Shift Registers
  - Pattern Generators
- Package Options Include Plastic Small-Outline (M) Package and Standard Plastic (E) DIP



## description

The CD74FCT273 is a positive-edge-triggered, D-type flip-flop with a direct clear ( $\overline{CLR}$ ) input. This device uses a small-geometry BiCMOS technology. The output stage is a combination of bipolar and CMOS transistors that limits the output high level to two diode drops below  $V_{CC}$ . This resultant lowering of output swing (0 V to 3.7 V) reduces power-bus ringing [a source of electromagnetic interference (EMI)] and minimizes  $V_{CC}$  bounce and ground bounce and their effects during simultaneous output switching. The output configuration also enhances switching speed and is capable of sinking 48 mA.

Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When CLK is at either the high or low level, the D input has no effect at the output. All eight flip-flops are controlled by a common clock (CLK) and a common reset ( $\overline{CLR}$ ). The outputs are placed in a low state when  $\overline{CLR}$  is taken low, independent of the CLK.

The CD74FCT273 is characterized for operation from 0°C to 70°C.

**FUNCTION TABLE**  
(each flip-flop)

INPUTS			OUTPUT Q
$\overline{CLR}$	CLK	D	
L	X	X	L
H	↑	H	H
H	↑	L	L
H	L	X	$Q_0$



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

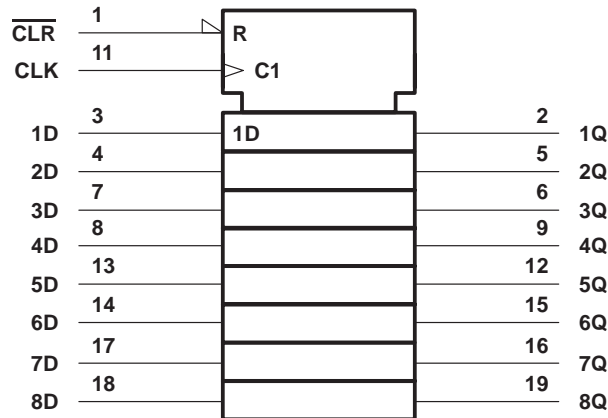
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# CD74FCT273 BiCMOS OCTAL D-TYPE FLIP-FLOP WITH RESET

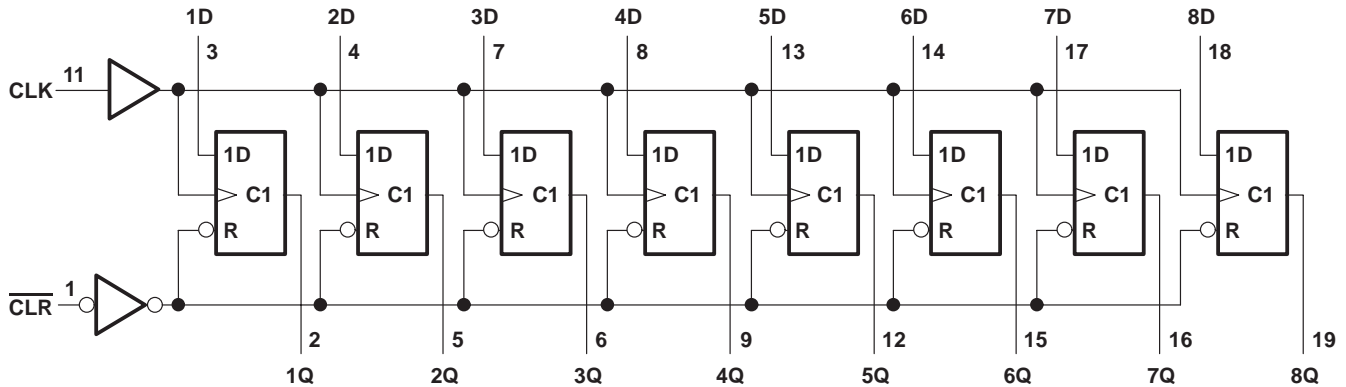
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## logic symbol†

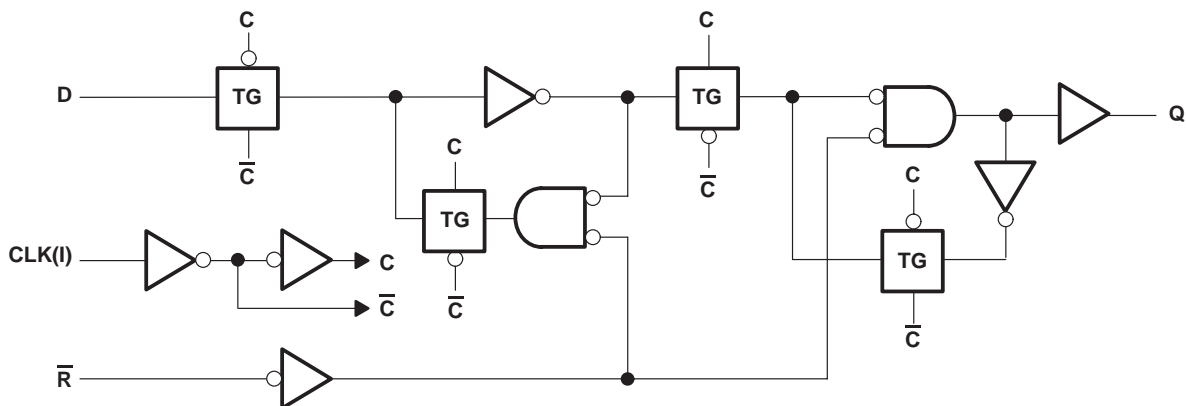


† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

## logic diagram (positive logic)



## logic diagram, each flip-flop (positive logic)



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

DC supply voltage range, $V_{CC}$ .....	–0.5 V to 6 V
DC input diode current, $I_{IK}$ ( $V_I < -0.5$ V) .....	–20 mA
DC output diode current, $I_{OK}$ ( $V_O < -0.5$ V) .....	–50 mA
DC output sink current per output pin, $I_{OL}$ .....	70 mA
DC output source current per output pin, $I_{OH}$ .....	–30 mA
Continuous current through $V_{CC}$ , $I_{CC}$ .....	140 mA
Continuous current through GND .....	400 mA
Package thermal impedance, $\theta_{JA}$ (see Note 1): E package .....	69°C/W
M package .....	58°C/W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51.

**recommended operating conditions (see Note 2)**

	MIN	MAX	UNIT
$V_{CC}$ Supply voltage	4.75	5.25	V
$V_{IH}$ High-level input voltage	2		V
$V_{IL}$ Low-level input voltage		0.8	V
$V_I$ Input voltage	0	$V_{CC}$	V
$V_O$ Output voltage	0	$V_{CC}$	V
$I_{OH}$ High-level output current		–15	mA
$I_{OL}$ Low-level output current		48	mA
$\Delta t/\Delta v$ Input transition rise or fall rate	0	10	ns/V
$T_A$ Operating free-air temperature	0	70	°C

NOTE 2: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**electrical characteristics over recommended operating temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	$V_{CC}$	$T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
			MIN	MAX			
$V_{IK}$	$I_I = -18$ mA	4.75 V		–1.2	–1.2		V
$V_{OH}$	$I_{OH} = -15$ mA	4.75 V	2.4		2.4		V
$V_{OL}$	$I_{OL} = 48$ mA	4.75 V		0.55	0.55		V
$I_I$	$V_I = V_{CC}$ or GND	5.25 V		$\pm 0.1$		$\pm 1$	$\mu\text{A}$
$I_{OZ}$	$V_O = V_{CC}$ or GND	5.25 V		$\pm 0.5$		$\pm 10$	$\mu\text{A}$
$I_{OS}^\ddagger$	$V_I = V_{CC}$ or GND, $V_O = 0$	5.25 V		–60	–60		mA
$I_{CC}$	$V_I = V_{CC}$ or GND, $I_O = 0$	5.25 V		8		80	$\mu\text{A}$
$\Delta I_{CC}^\S$	One input at 3.4 V, Other inputs at $V_{CC}$ or GND	5.25 V		1.6		1.6	mA
$C_i$	$V_I = V_{CC}$ or GND					10	pF

‡ Not more than one output should be tested at a time, and the duration of the test should not exceed 100 ms.

§ This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or  $V_{CC}$ .

**CD74FCT273**  
**BiCMOS OCTAL D-TYPE FLIP-FLOP**  
**WITH RESET**

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**timing requirements over recommended operating conditions (unless otherwise noted) (see Figure 1)**

		MIN	MAX	UNIT
f <sub>clock</sub>	Clock frequency		70	MHz
t <sub>w</sub>	Pulse duration	CLR low	7	ns
		CLK high or low	7	
t <sub>su</sub>	Setup time	Data before CLK↑	3	ns
		CLR before CLK↑	4	
t <sub>h</sub>	Hold time	Data after CLK↑	2	ns

**switching characteristics over recommended operating conditions, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

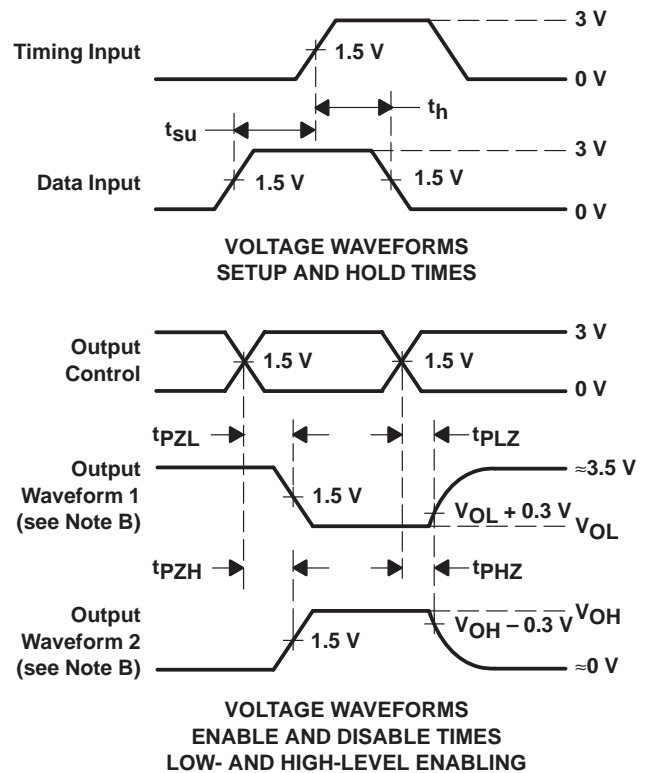
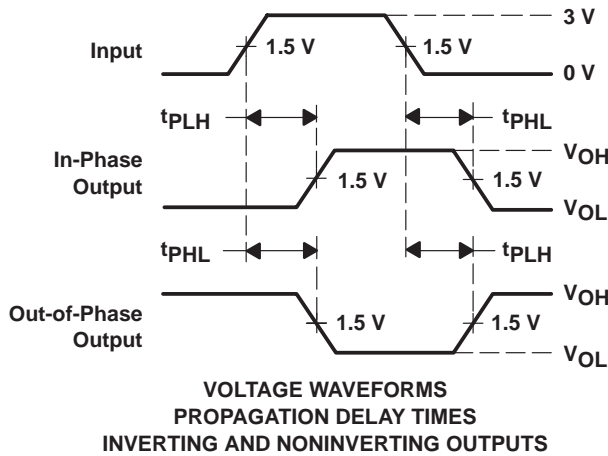
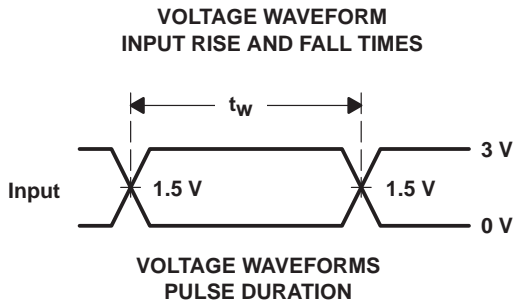
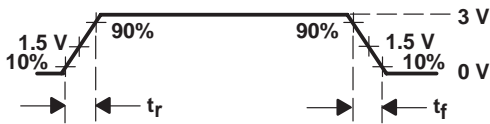
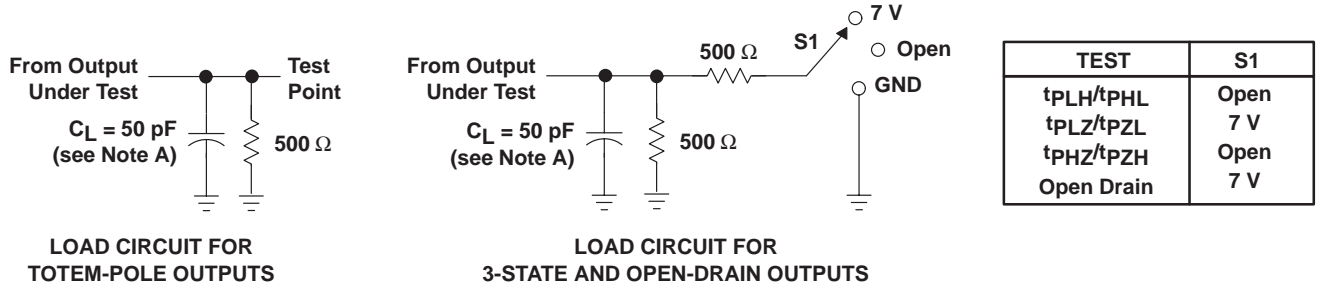
PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25°C	MIN	MAX	UNIT
			TYP			
f <sub>max</sub>				70		MHz
t <sub>pd</sub>	CLK	Any Q	7	2	13	ns
	CLR		8	2	13	

**operating characteristics, T<sub>A</sub> = 25°C**

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance	No load, f = 1 MHz	36	pF



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C<sub>L</sub> includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z<sub>O</sub> = 50 Ω, t<sub>r</sub> and t<sub>f</sub> = 2.5 ns.  
 D. The outputs are measured one at a time with one input transition per measurement.  
 E. t<sub>PLZ</sub> and t<sub>PHZ</sub> are the same as t<sub>dis</sub>.  
 F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.  
 G. t<sub>PHL</sub> and t<sub>PLH</sub> are the same as t<sub>pd</sub>.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
CD74FCT273-W	ACTIVE	WAFERSALE	YS	0	4266	TBD	Call TI	Call TI			<a href="#">Samples</a>
CD74FCT273E	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	CD74FCT273E	<a href="#">Samples</a>
CD74FCT273EE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	CD74FCT273E	<a href="#">Samples</a>
CD74FCT273M	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74FCT273M	<a href="#">Samples</a>
CD74FCT273ME4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74FCT273M	<a href="#">Samples</a>
CD74FCT273MG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	74FCT273M	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



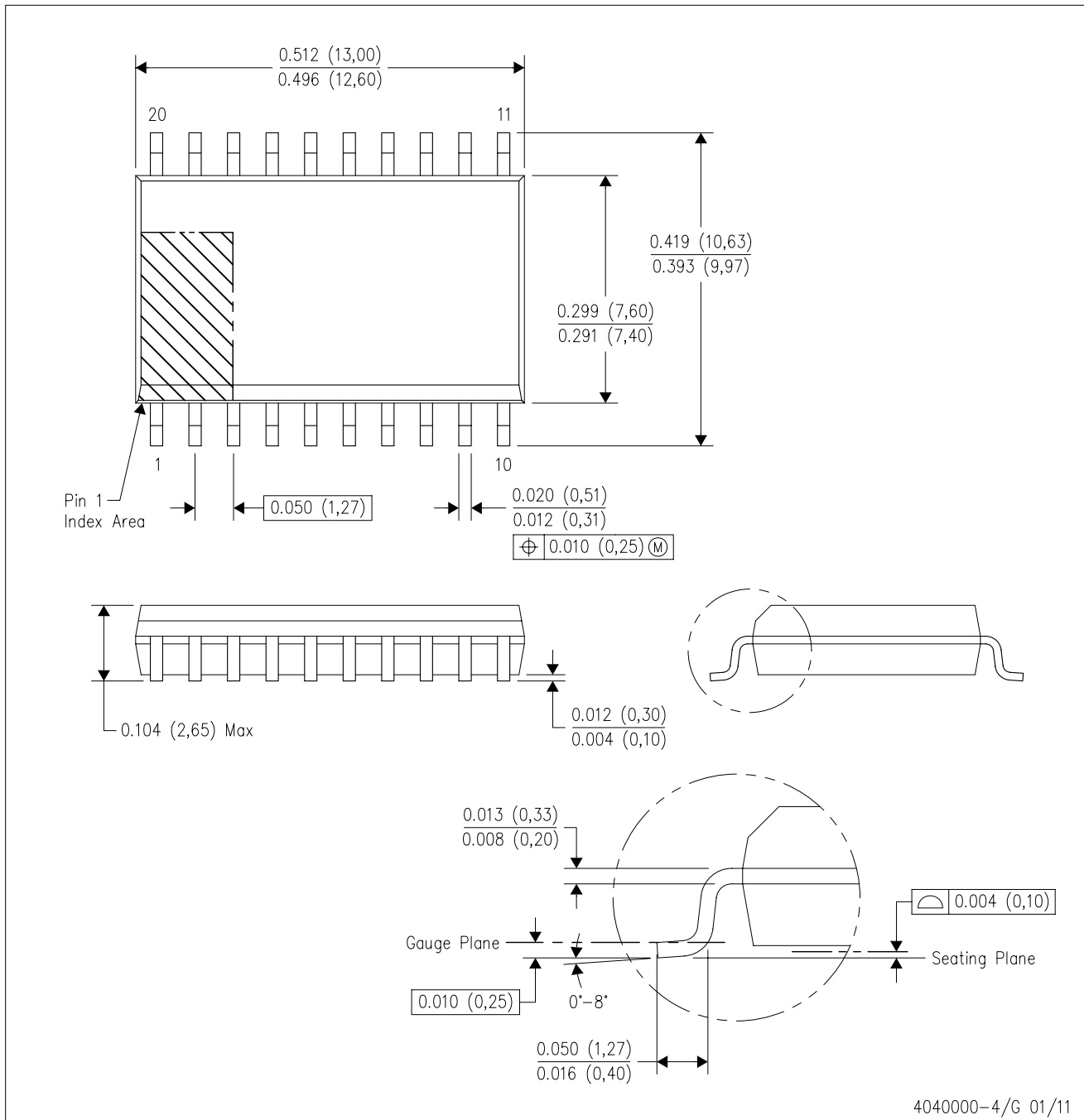
- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

4040049/E 12/2002



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
  - This drawing is subject to change without notice.
  - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - Falls within JEDEC MS-013 variation AC.

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